INTRODUCTION TO X-RAY CT Aya Takase @ Rigaku



V Session ... Preference

4-1

1-7-7-0-8-8-55

0 🔲 5

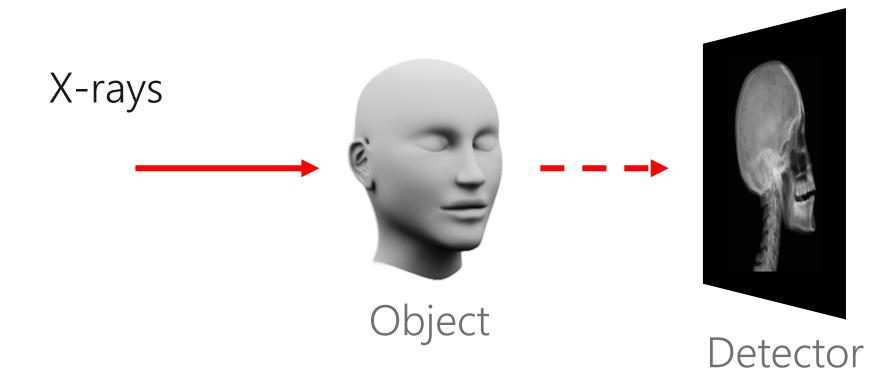
You will learn:
How X-ray CT works
Common challenges
Different types of CT scanners
Applications



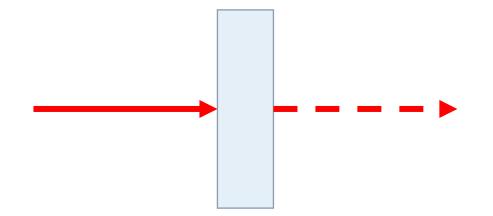
HOW DOES IT WORK? – LET'S START WITH 2D –



2D projection

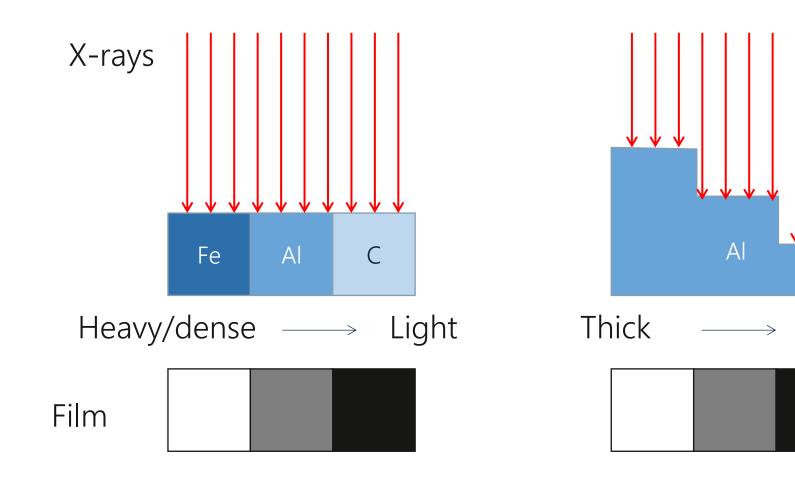






Things absorb X-rays.



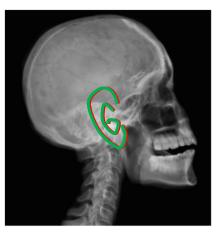




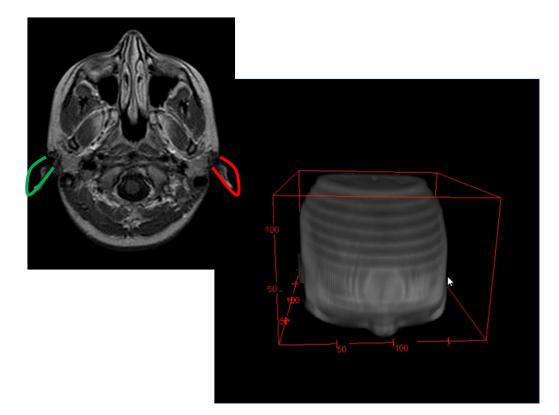
Thin

HOW DO YOU GET 3D VIEW?



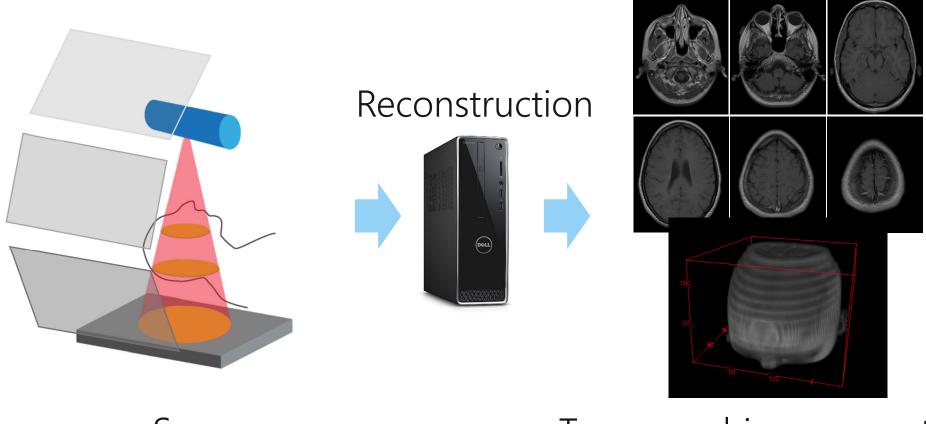






3D computed tomography





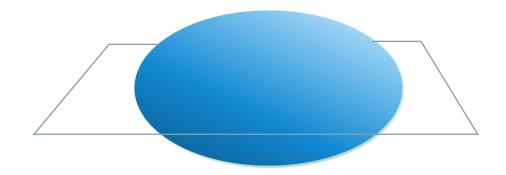
Scan

Tomographic cross sections 3D rendering

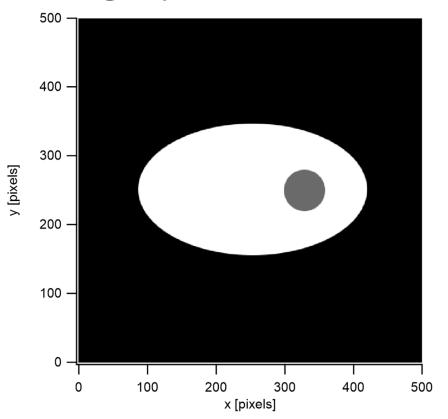


HOW DOES RECONSTRUCTION WORK?

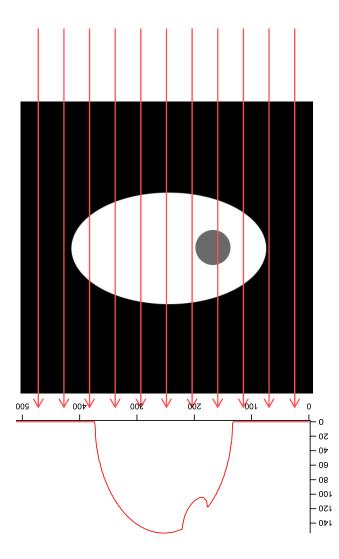




Tomographic cross section

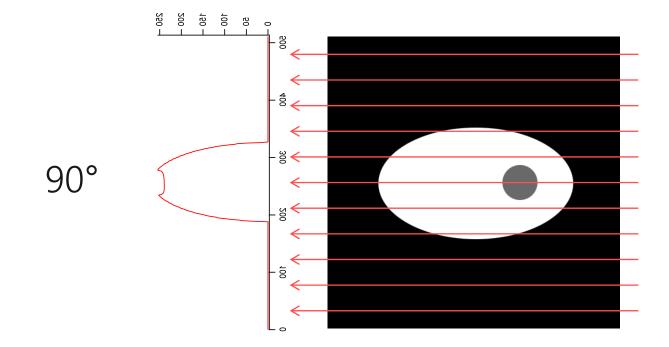




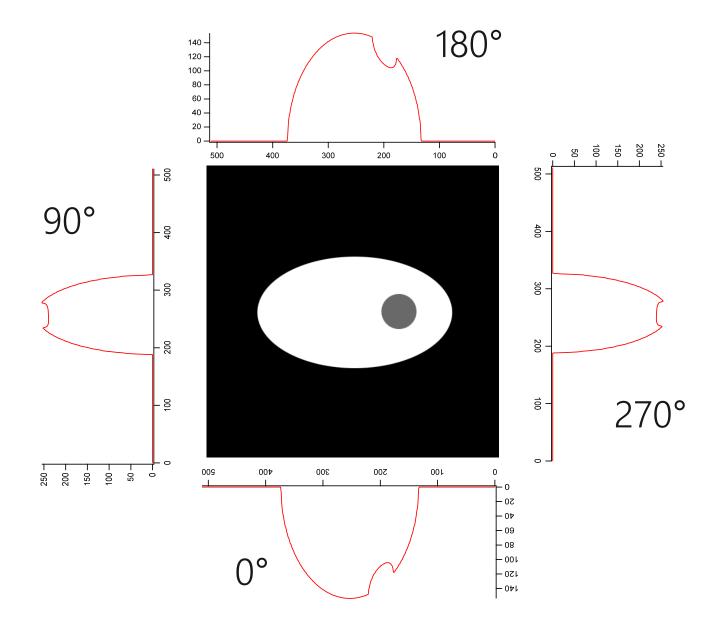


Integrated density projection angle 0°



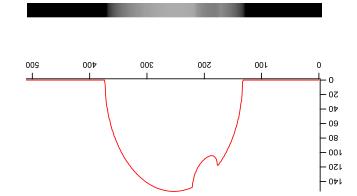




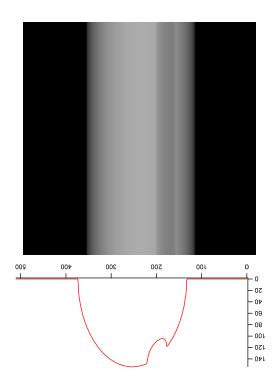


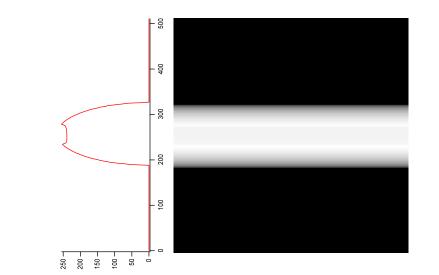


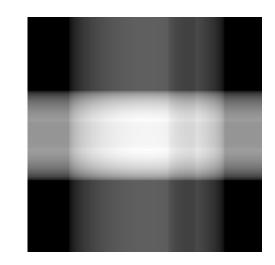




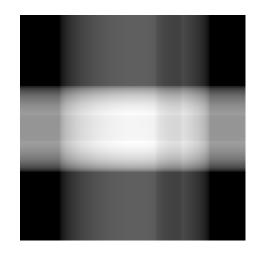


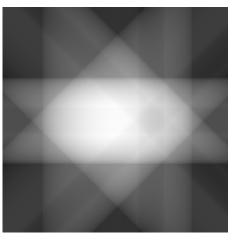


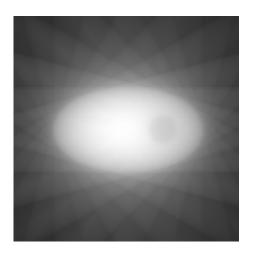


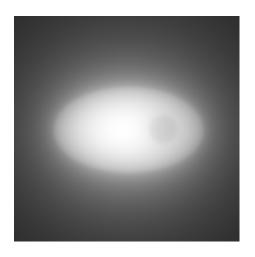






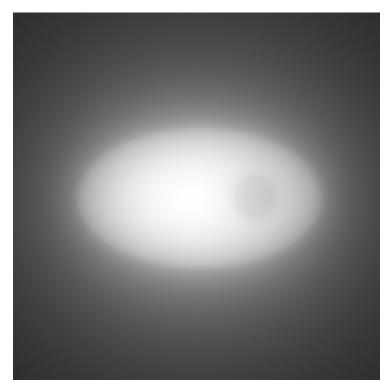




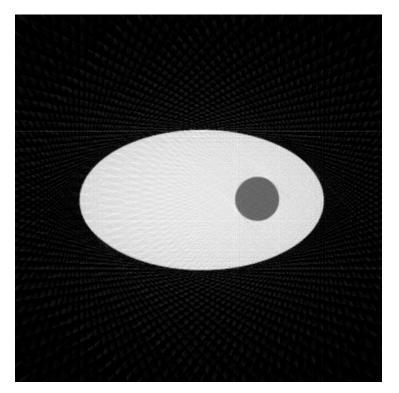


4 projections 8 projections 24 projections 120 projections



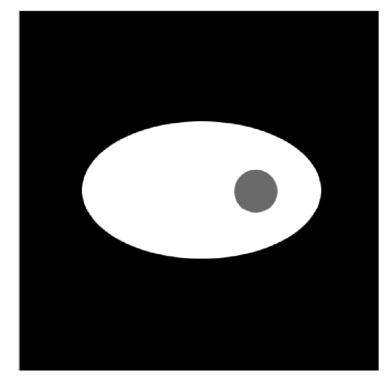


120 projections

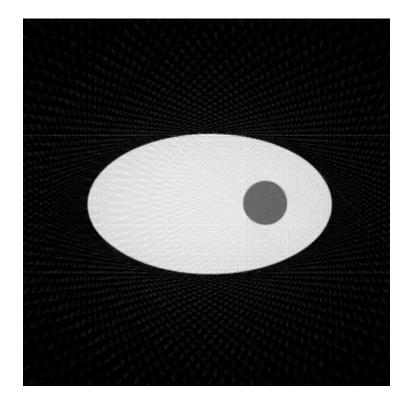


120 projections With ramping filter



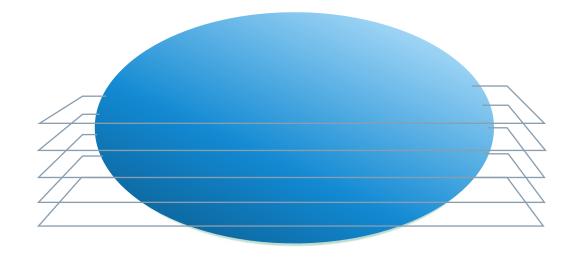


Original

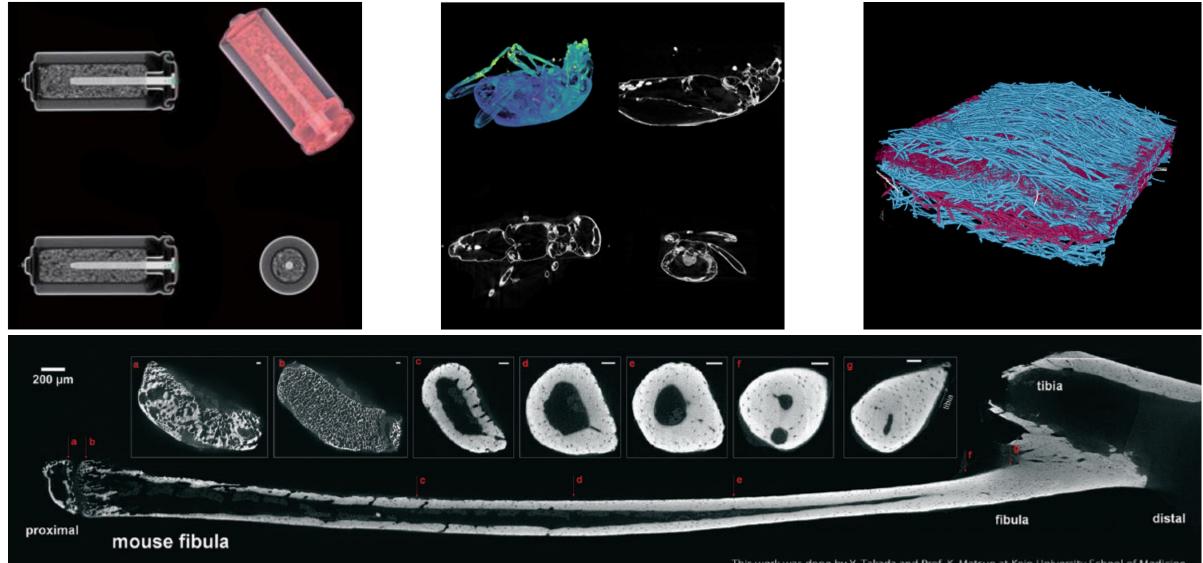


Reconstructed









This work was done by Y. Takada and Prof. K. Matsuo at Keio University School of Medicine.



WHAT ARE THE COMMON CHALLENGES?



COMMON CHALLENGES

- Limited resolution compared to EM
- Too light / heavy absorbing materials
- Artifacts





COMMON CHALLENGES

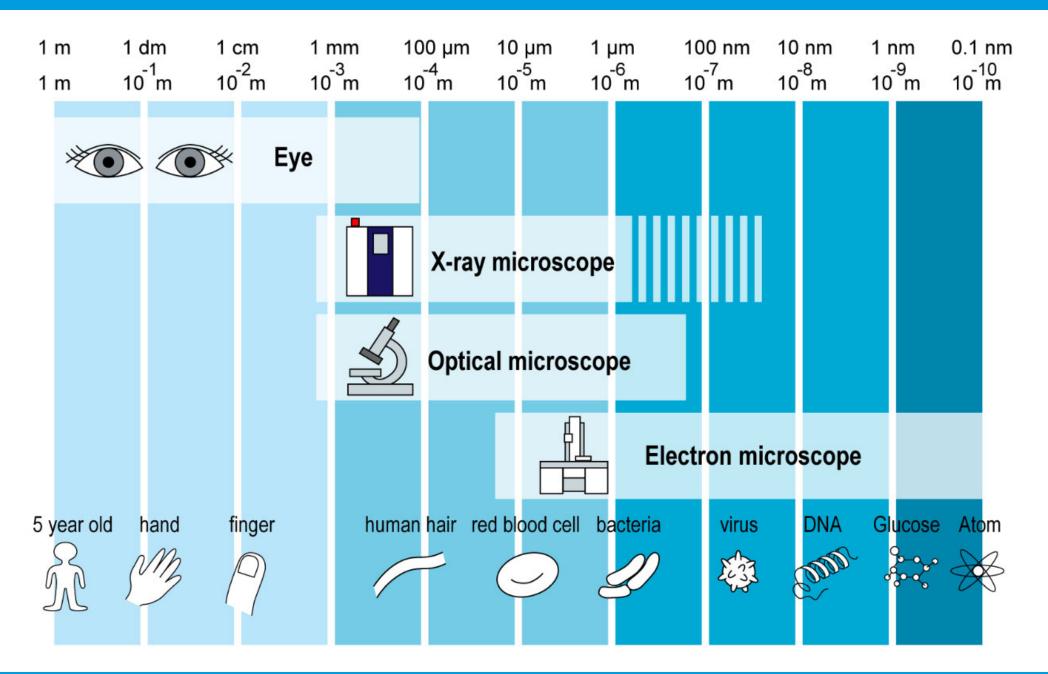
- Limited resolution compared to EM
- Too light / heavy absorbing materials
- Artifacts





WHAT'S THE RESOLUTION?







COMMON CHALLENGES

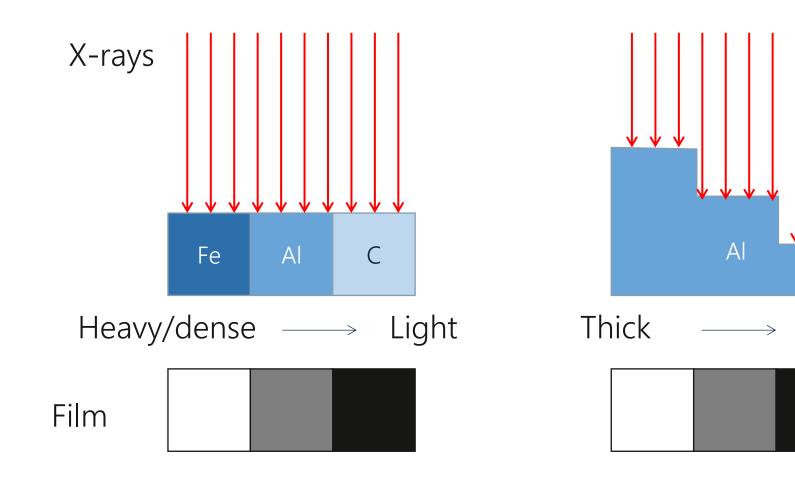
- Limited resolution compared to EM
- Too light / heavy absorbing materials
- Artifacts





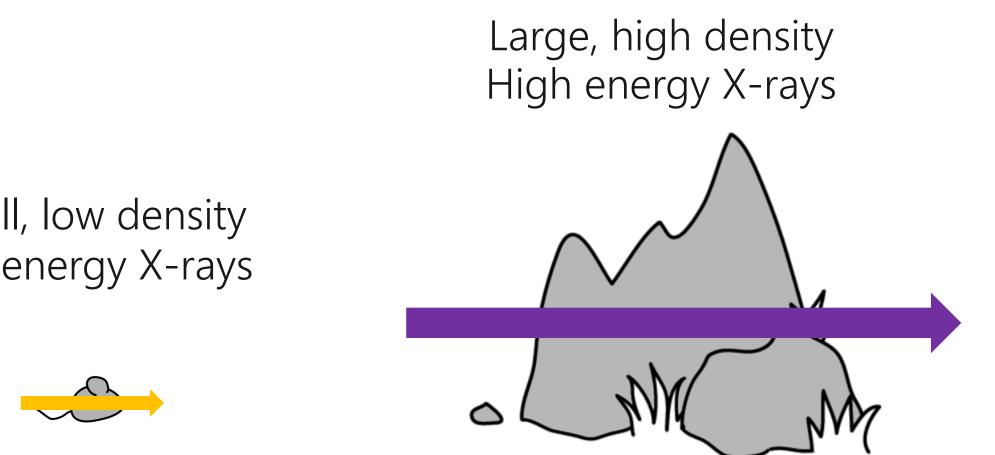
WHAT'S TOO LIGHT OR TOO HEAVY?





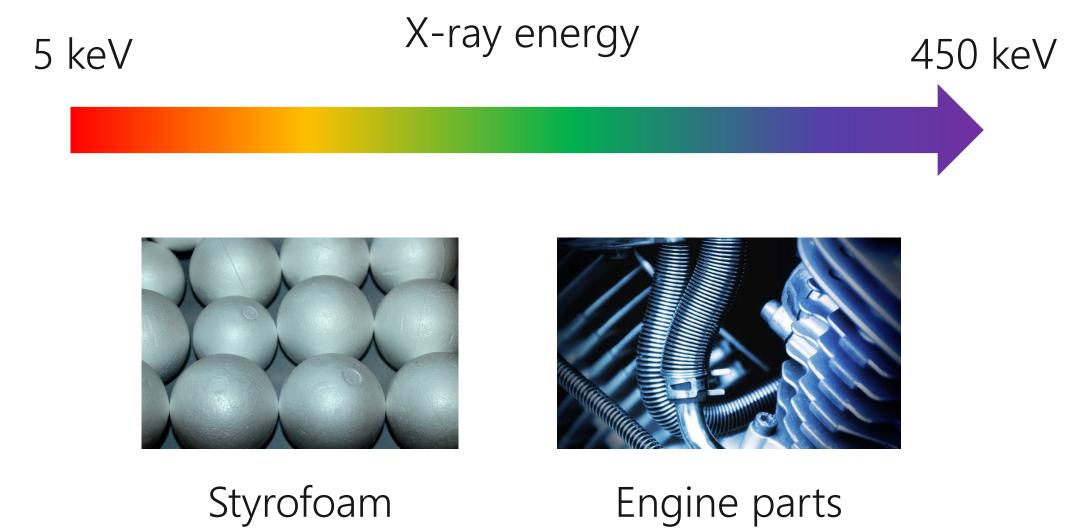


Thin









~ 5 keV

Engine parts ~ 450 keV



COMMON CHALLENGES

- Limited resolution compared to EM
- Too light / heavy absorbing materials
- Artifacts

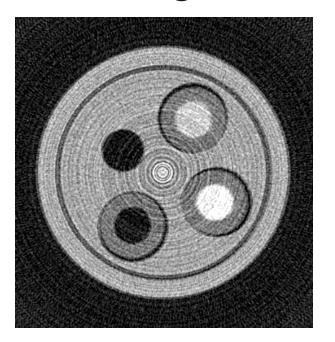




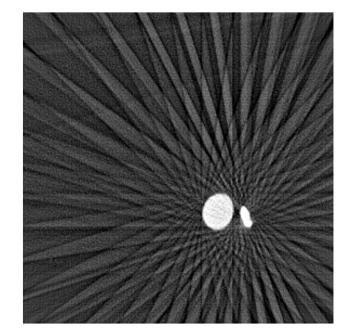
WHAT ARE ARTIFACTS?



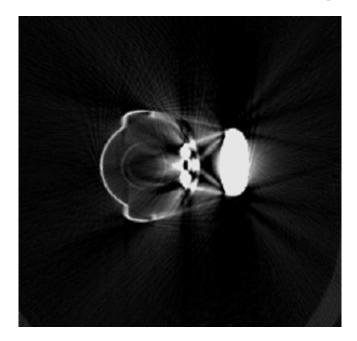




Aliasing



Streaks & shading



Bad pixels

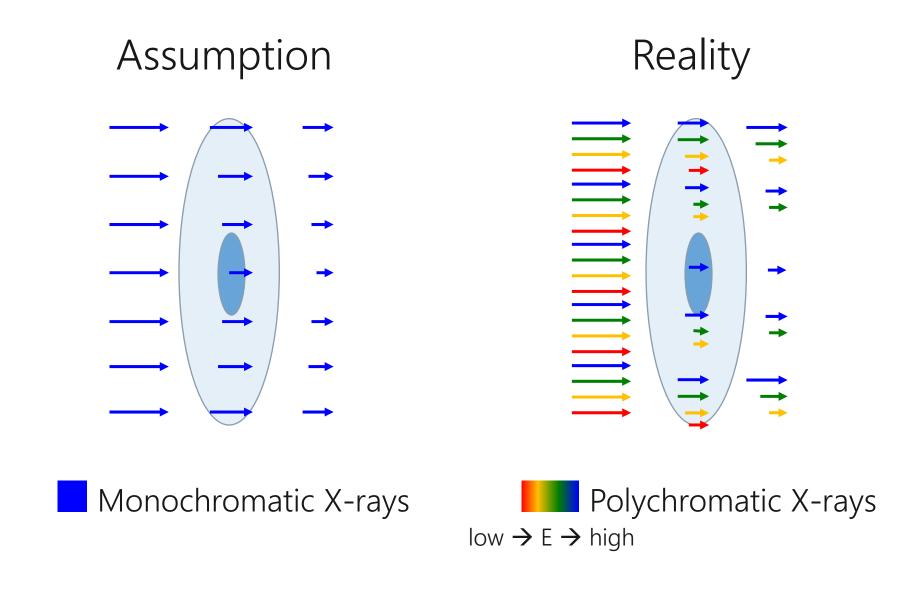
Under sampling

Beam hardening



WHAT IS BEAM HARDENING?







BEAM HARDENING ARTIFACTS SIMULATION

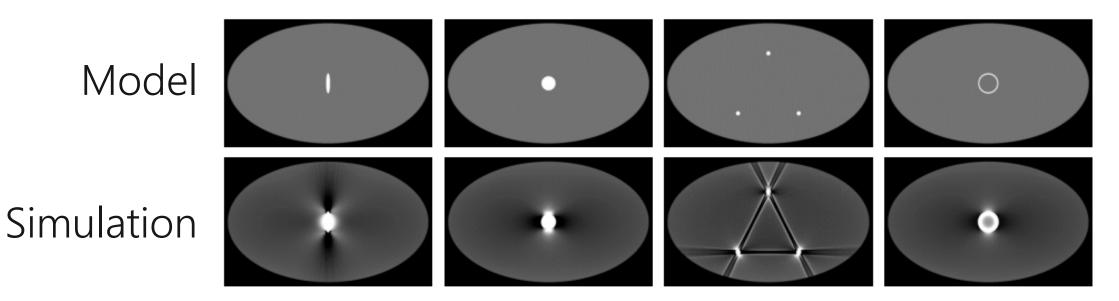


Figure 4. Simulated scans without (top row) and with (bottom row) beam hardening, showing that dark streaks occur along the lines of greatest attenuation, and bright streaks occur in other directions. Scatter produces artifacts that look similar to this. Also note the subtle decrease in Hounsfield units just beneath the surface of the "abdomen," which is caused by beam hardening. This is called cupping artifact, and it is corrected by the simple beam hardening correction built into modern scanners.

Imaging Med. (2012) 4(2), 229-240



COMMON CHALLENGES

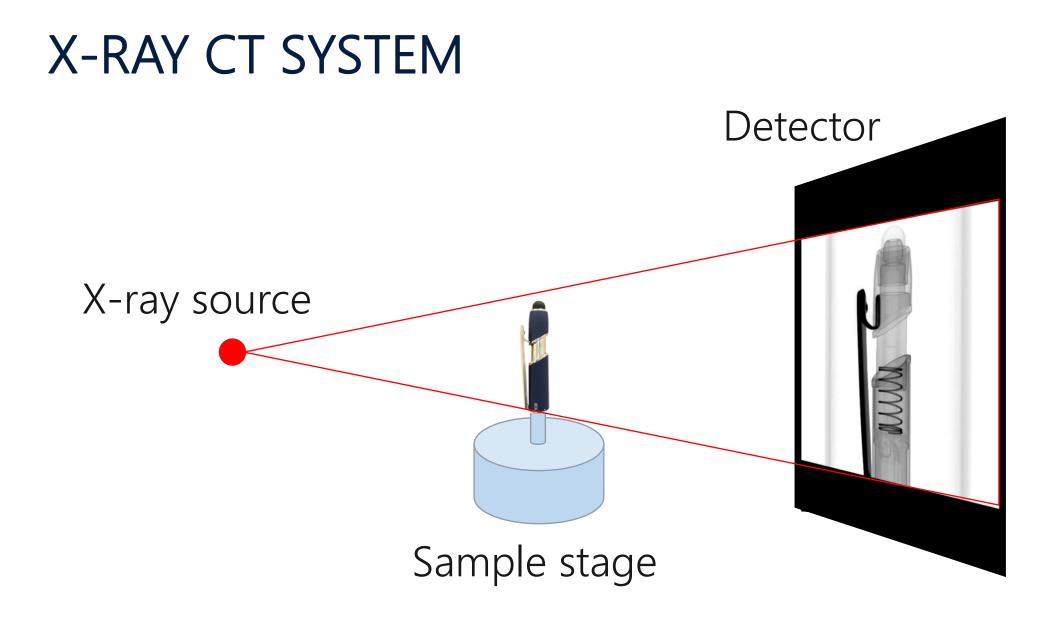
- Limited resolution compared to EM
- Too light / heavy absorbing materials
- Artifacts





WHAT HARDWARE IS INVOLVED IN AN X-RAY CT SYSTEM?







MICROFOCUS X-RAY SOURCES





Hamamatsu Photonics

Low energy, high power 5.4, 8, 17 keV 1200 W

Medium energy 60 ~ 190 kV ~ 100 W



High energy 190 ~ 750 kV ~ 450 W



DETECTORS



Rayence



Flat panel detector Fast, sensitive, inexpensive 50 ~ 200 µm CCD High resolution 2.4 ~ 15 µm



sCMOS Fast, sensitive 6.5 µm ~



- X-ray energy
- Field of view (FOV)
- Resolution (voxel size)

- X-ray power
- Detector speed and efficiency



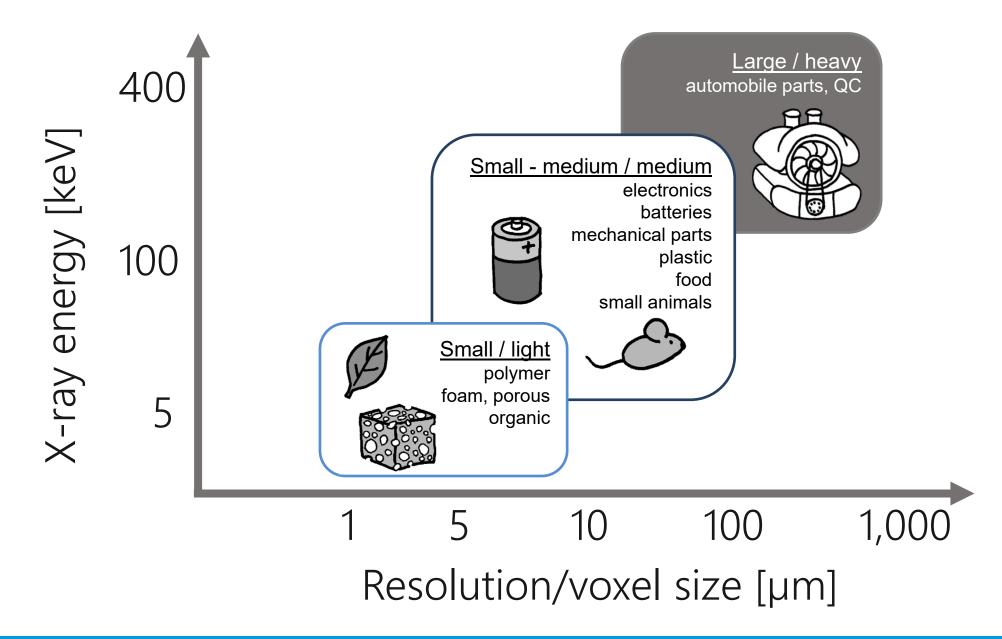


- X-ray energy
- Field of view (FOV)
- Resolution (voxel size)

- X-ray power
- Detector speed and efficiency







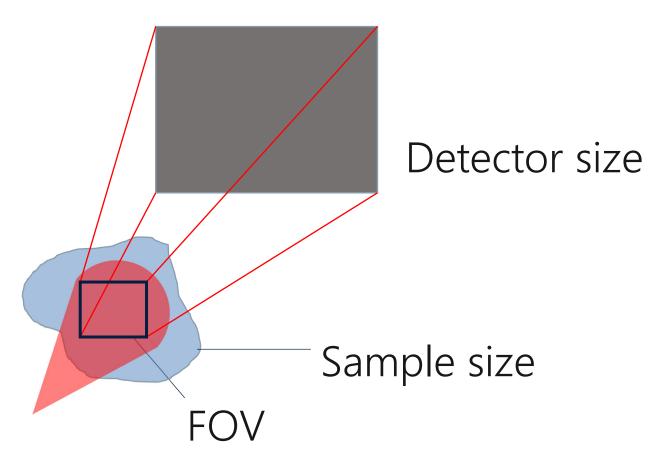


- X-ray energy
- Field of view (FOV)
- Resolution (voxel size)

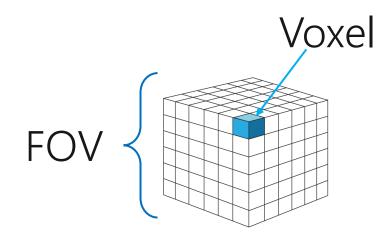
- X-ray power
- Detector speed and efficiency









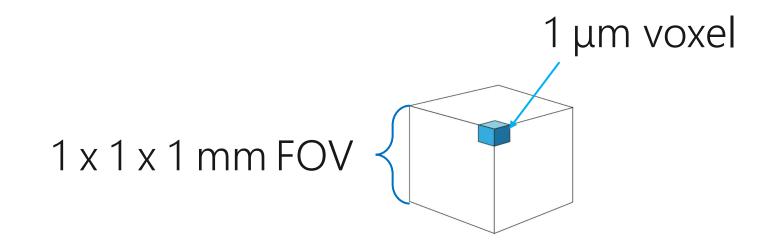


Small FOV, small voxel

Large FOV, large voxel



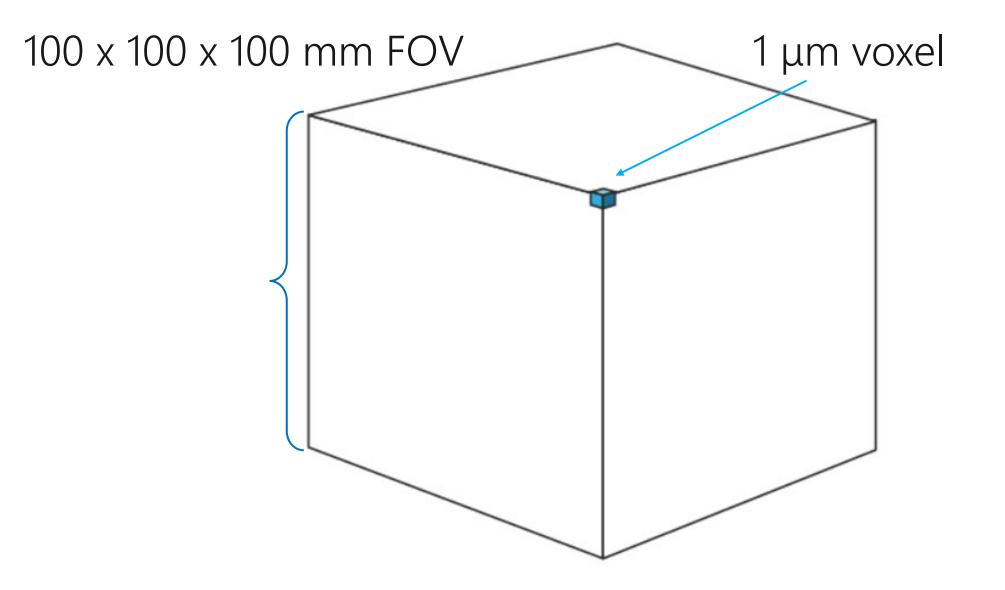






FOV [mm]	Voxel [µm]	Bit	File size
1 x 1 x 1	1	16	2 GB

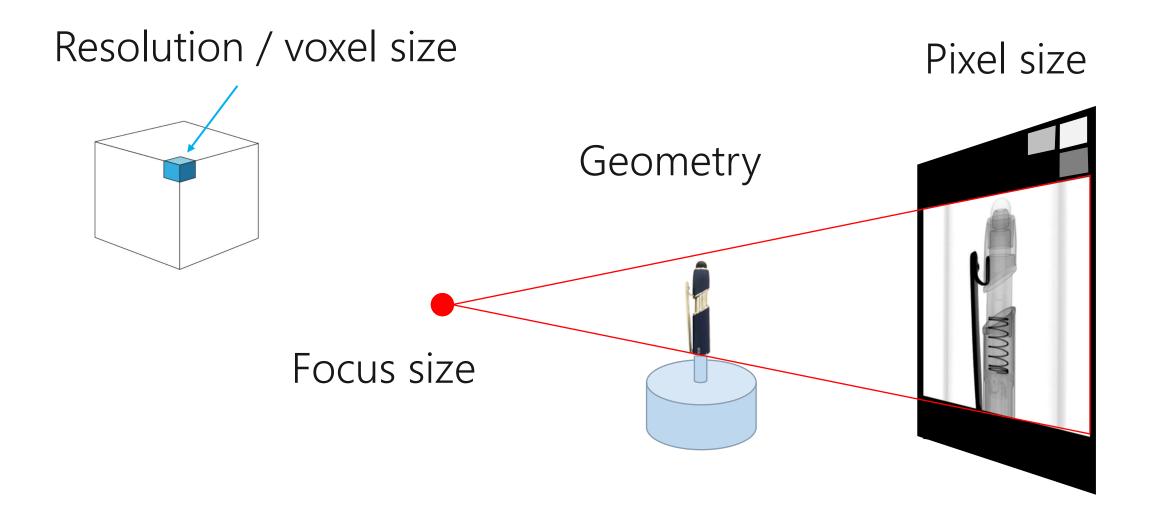






FOV [mm]	Voxel [µm]	Bit	File size
1 x 1 x 1	1	16	2 GB

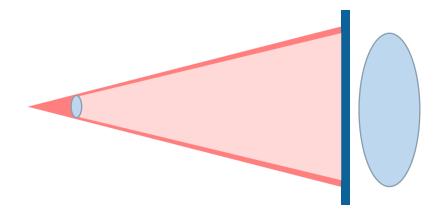


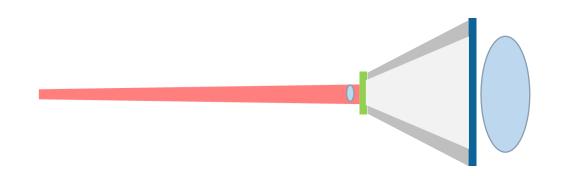




HOW DOES MAGNIFICATION WORK?





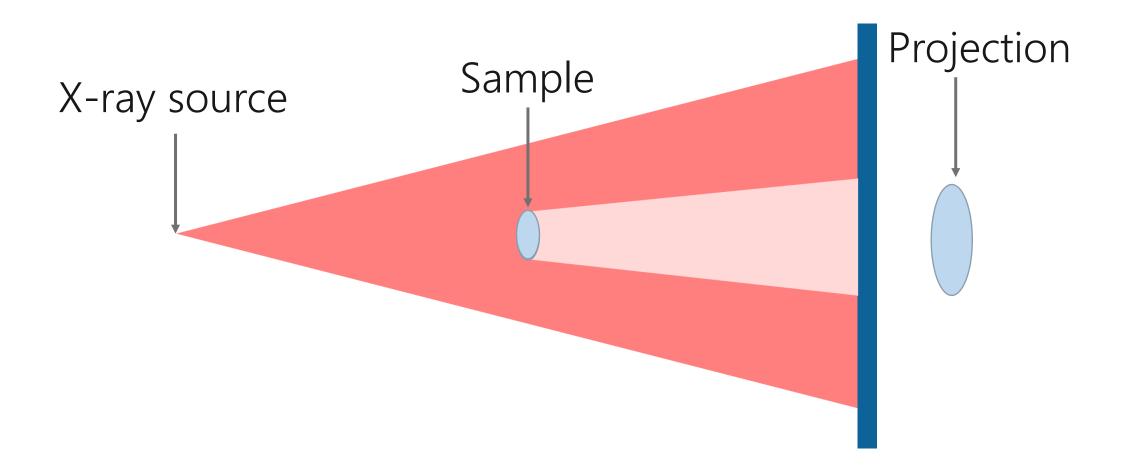


Cone beam

Parallel beam



CONE BEAM - MECHANICAL MAGNIFICATION





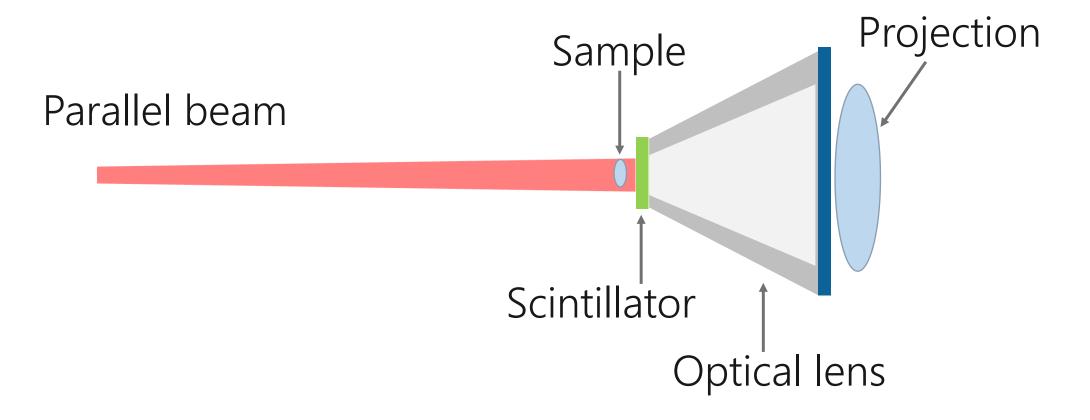
CONE BEAM - MECHANICAL MAGNIFICATION

Versatile, inexpensive



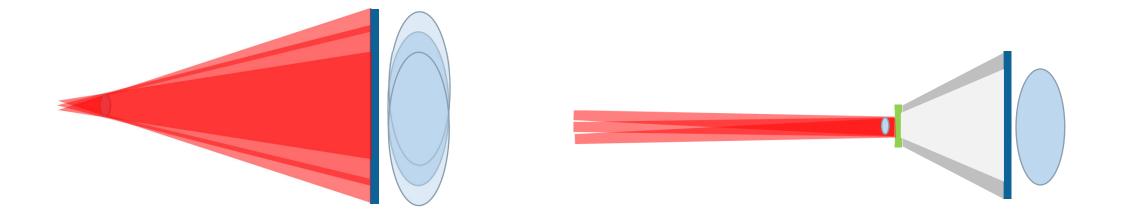
PARALLEL BEAM - OPTICAL MAGNIFICATION

High resolution, requires high power source





CONE BEAM VS. PARALLEL BEAM



Cone beam

Parallel beam Immune to drift \rightarrow high resolution



- X-ray energy
- Field of view (FOV)
- Resolution (voxel size)

- X-ray power
- Detector speed and efficiency



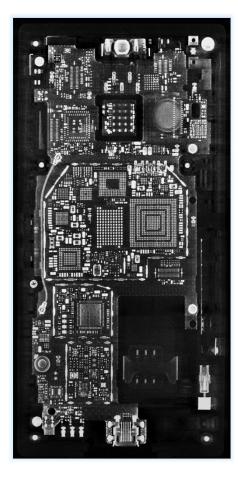


ANY EXAMPLES?

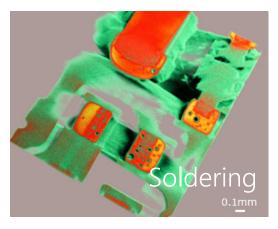


ELECTRONICS









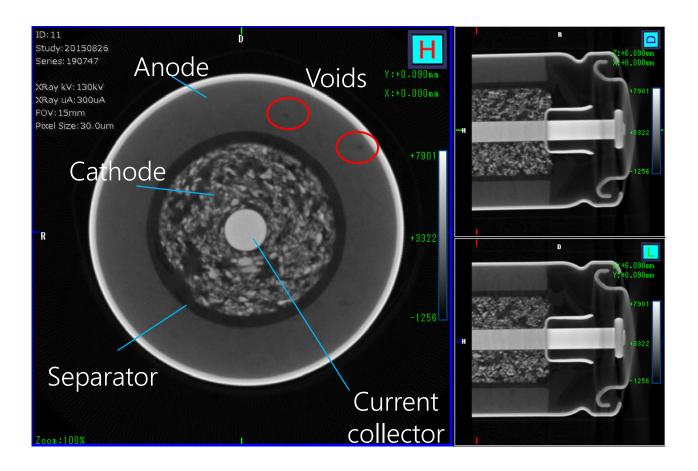


BATTERIES





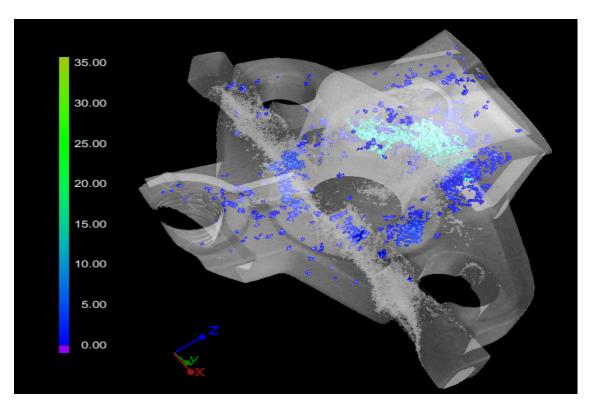






ALUMINUM DIE CASTINGS

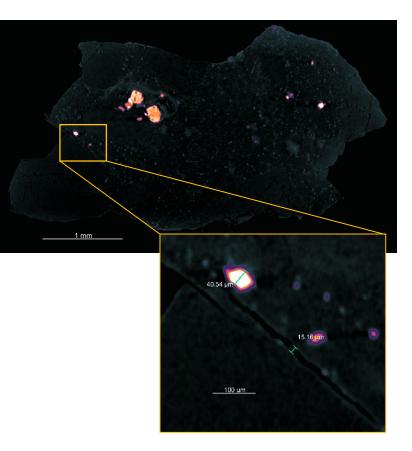
Volume analysis Total: 2762.56 mm³ Void: 32.81 mm³ → 1.17%





ROCKS

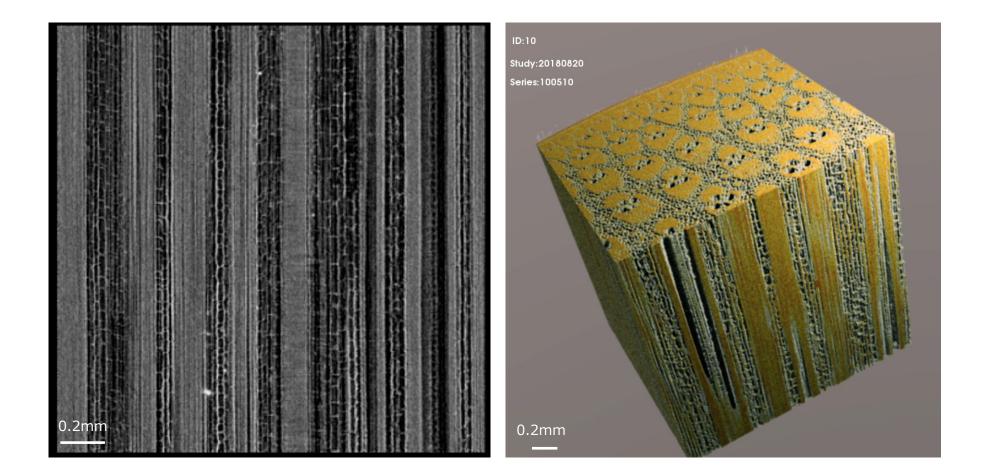




Cracks and inclusions

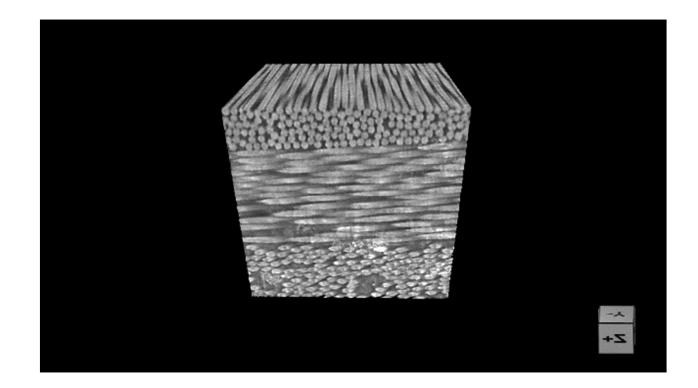


PLANTS



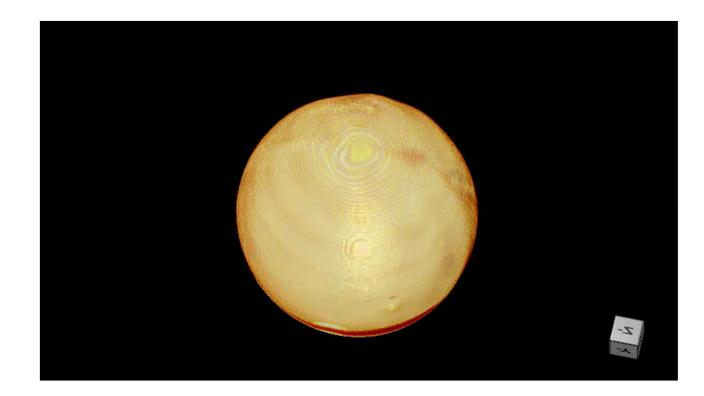


COMPOSITES









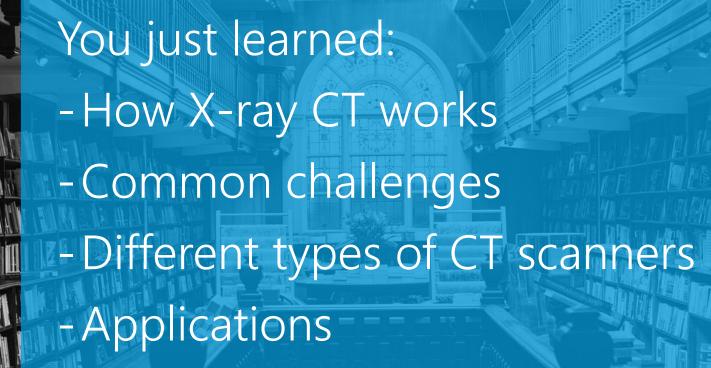


Electronics Ceramics & rocks Light metals

Composites Plants & insects Food & pharmaceuticals













To learn more Visit imaging.rigaku.com







THANK YOU FOR JOINING US!

To learn more visit imaging.Rigaku.com

